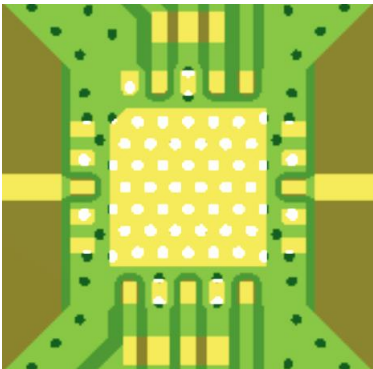
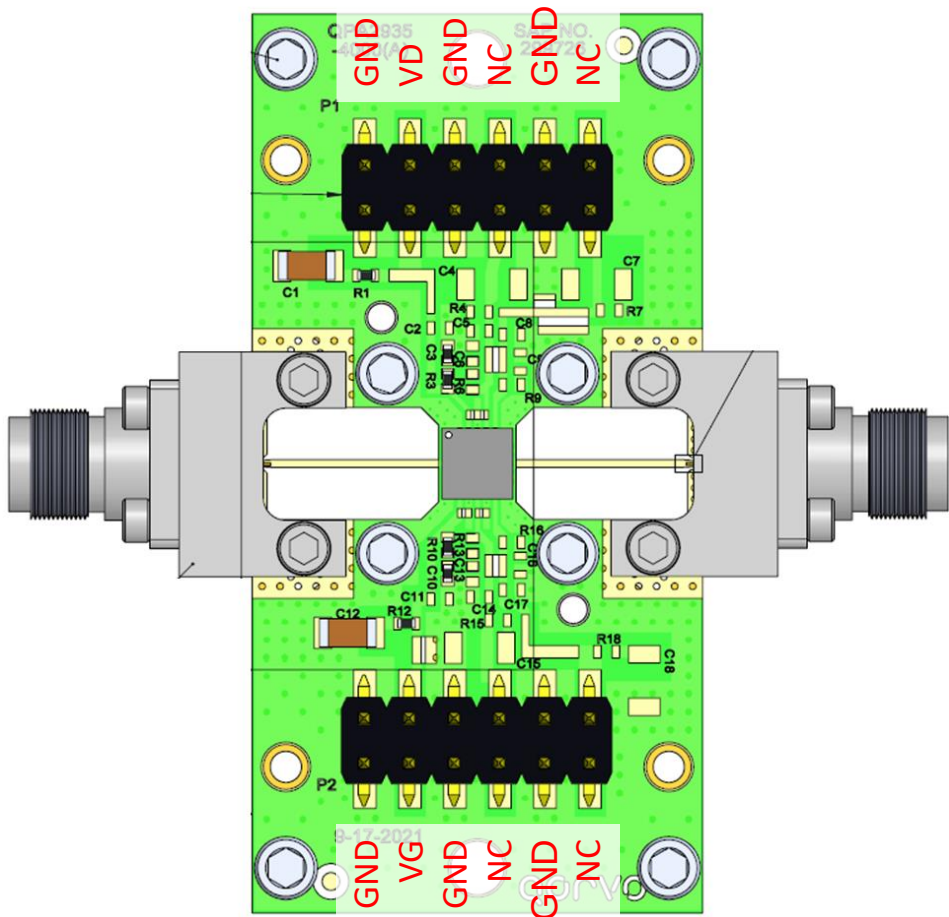


Evaluation Board (EVB) Layout Assembly



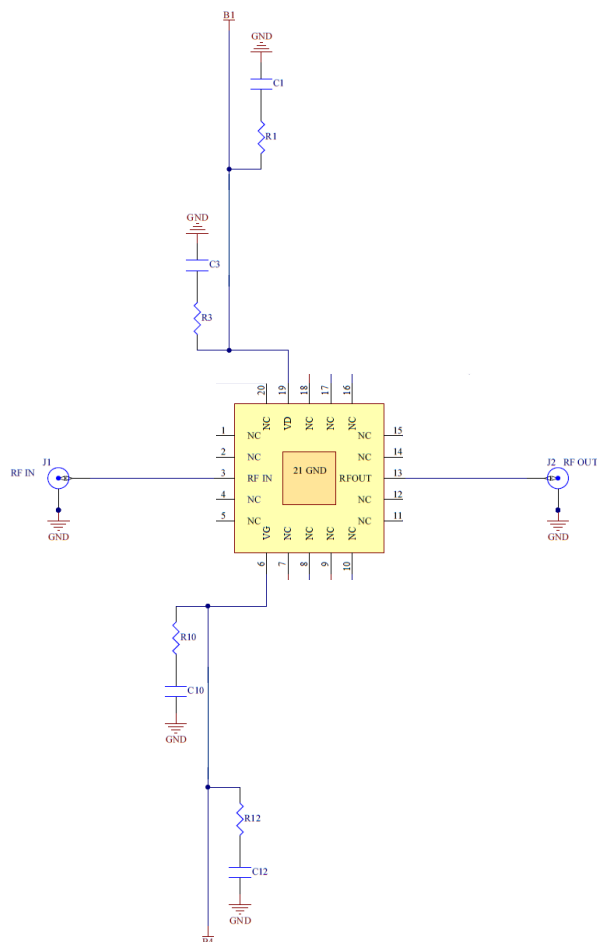
Package Mounting Detail

Thermal vias under the DUT are copper filled and over-plated for improved thermal management.
Copper layers are 0.5 oz. both sides. PCB material is Rogers Corp. R4003C, .008 in. thick

Bill of Materials

Reference Des.	Value	Description	Manuf.	Part No.
C1, C12	1.0 uF	CAP, 1uF, 5% 50V, X7R, 1206	Various	
C3, C10	1000 pF	CAP, 1000pF, 10%, 100V, X7R, 0402	Various	
R1, R3, R10, R12	10 Ohm	RES, 10 OHM, 5%, 0.1W, 0402	Various	
J1, J2	2.92 mm	CONN, 2.92, END, F, PIN .005, DIELECT .029	Southwest Microwave	1092-01A-5

Applications Information



Bias-Up Procedure

Set V_D supply limit to 300 mA, V_G limit to 30 mA

Turn on V_G supply and set $V_G = -4$ V

Turn on V_D supply and set $V_D = 0$ V

Adjust V_D to 25 V

Adjust V_G to obtain desired I_{DQ} and apply RF

Bias-Down Procedure

Turn off RF source

Set $V_G = -4$ V

Set $V_D = 0$ V

Turn off V_D Supply

Turn off V_G Supply